TOSHIBA 2SJ525

TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE ($L^2-\pi$ -MOS V)

S J 5 2 5

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

• 4 V Gate Drive

• Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.1 \Omega \text{ (Typ.)}$

• High Forward Transfer Admittance $: |Y_{fs}| = 4.5 \text{ S (Typ.)}$

• Low Leakage Current : $I_{DSS} = -100 \,\mu A$ (Max.)

 $(V_{DS} = -30 V)$

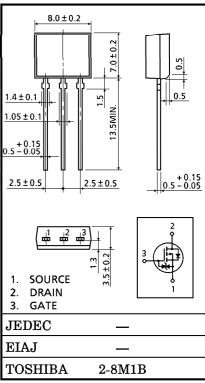
: $V_{th} = -0.8 \sim -2.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = -10 V, I_{D} = -1 mA)$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$v_{ m DSS}$	-30	V	
Drain-Gate Voltage (RGS	$v_{ m DGR}$	-30	V	
Gate-Source Voltage	v_{GSS}	±20	V	
Drain Current	DC	$I_{\mathbf{D}}$	-5	A
	Pulse	$I_{ m DP}$	-20	A
Drain Power Dissipation (Ta = 25°C)	PD	1.3	w	
Single Pulse Avalanche	EAS	517	mJ	
Avalanche Current	I_{AR}	- 5	A	
Repetitive Avalanche En	E_{AR}	0.13	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Ra	$\mathrm{T_{stg}}$	-55~150	$^{\circ}\mathrm{C}$	

INDUSTRIAL APPLICATIONS Unit in mm



Weight: 0.54 g (Typ.)

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	96.1	°C/W

* Repetitive rating; Pulse Width Limited by Max. junction temperature.

** $V_{DD} = -25 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 14.84 mH, $R_G = 25 \Omega$, $I_D = -5 \text{ A}$

This transistor is an electrostatic sensitive device. Please handle with caution.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

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CHARA	ACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakag	ge Current	I_{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μ A
Drain Cut-off Current		$I_{ m DSS}$	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-100	μ A
Drain-Source Voltage	e Breakdown	V (BR) DSS	$I_{ m D} = -10 { m mA}, \; { m V}_{ m GS} = 0 { m V}$	-30	_	_	V
Gate Thresh	old Voltage	$V_{ m th}$	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-Source	e ON Resistance	R _{DS} (ON)	$V_{GS} = -4 \text{ V}, I_D = -2.5 \text{ A}$ $V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	_	0.17	$0.2 \\ 0.12$	Ω
Forward Tra Admittance	ınsfer	$ Y_{fs} $	$V_{ m DS} = -10 m V, I_{ m D} = -2.5 m A$	2.0	4.5	_	s
Input Capacitance		C_{iss}		_	850	_	
Reverse Transfer Capacitance		$\mathrm{C}_{ extbf{rss}}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	_	250	_	pF
Output Capacitance		Coss		_	330		
Switching Time	Rise Time	t _r	V_{GS} V_{OUT} V_{OUT}		50	_	
	Turn-on Time	t _{on}	V_{GS} V_{OUT} V_{OUT} $V_{DD} = -2.5 \text{ A}$ V_{OUT} V_{OUT} $V_{DD} = -15 \text{ V}$ $V_{IN}: t_r, t_f < 5 \text{ ns},$	_	75	_	ns
	Fall Time	tf		_	20	_	
	Turn-off Time	t _{off}	$V_{\mathrm{IN}}: \mathrm{t_r}, \mathrm{t_f} < 5 \mathrm{ns}, \ \mathrm{Duty} \leq 1\%, \mathrm{t_W} = 10 \mu \mathrm{s}$	_	95	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		\mathbf{Q}_{g}	$V_{\mathrm{DD}} = -24 \mathrm{V}, V_{\mathrm{GS}} = -10 \mathrm{V},$	_	27	_	»C
Gate-Source Charge		Q_{gs}	$I_{\rm D} = -5 \mathrm{A}$	_	19	_	nC
Gate-Drain ("Miller") Charge		$Q_{ m gd}$			8	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	-5	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	-20	A
Diode Forward Voltage	$ m v_{DSF}$	$I_{DR} = -5 A$, $V_{GS} = 0 V$	_	_	1.7	V
Reverse Recovery Time	t_{rr}	$I_{DR} = -5 A$, $V_{GS} = 0 V$		60	_	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt = 50 A/\mu s$	_	56		nC

MARKING

